



DRW
PATENT

Atty. Dkt. No. APPM/003421.C2/PPC/ECP/CKIM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Cheung, et al.

Serial No.: 10/686,486

Confirmation No.: 8014

Filed: October 15, 2003

For: Apparatus for Electro
Chemical Deposition of
Copper Metallization with
the Capability of In-Situ
Thermal Annealing

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Group Art Unit: 1742

Examiner: Harry D. Wilkins, III

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>4/11</u> , 2006 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<u>4/11/06</u> Date	<u>Keith M. Tackett</u> Keith M. Tackett

RESPONSE TO OFFICE ACTION DATED JANUARY 11, 2006

In response to the Office Action dated January 11, 2006, having a shortened statutory period for response set to expire on April 11, 2006, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/003421.C2/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 6 of this paper.